

SEA & LAND ELECTRONIC CORP.

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ALPHA-TOP TECHNOLOGY CORP.

WWW.ALPHA-TOP.CN

APPROVAL SHEET

MODEL NO.:	SMD1210-110-13.2V	
CUSTOMER:		
CUSTOMER'S	APPROVAL:	
AUTHORIZED	SIGNATURE/STAMP:	
DATE		

MANUFACTURER:

HEAD OFFICE:

13F.,No.120-10,Sec.3,Zhongshan Rd.,Zhonghe Dist.,New Taipei City 23544,Taiwan

Tel: 886-2-8221-2567 Fax:882-2-2225-7268

E-mail:service@chipfast.com.tw

China Branch:

Factory Building B)Shuangpeng,Weibu Village, Qiuchang Town, Huiyang District, Huizhou City, Guangdong Province, P.R.C.)

Tel: 86-752-3562001 Fax:86-752-3558696 E-mail:service@atpptc.com

Submitted by: Chung Cheng Approved by: YC Lin DATE: 15-Sep-21

SEA & LAND ELECTRONIC CORP.



■ Surface Mount Devices

■ Lead free device

■ Surface Mount packaging

Applications

Almost anywhere there is a low voltage power supply, up to 30V and a load to be

protected, including:

■ Computer mother board, Modem.

SMD1210-110-13.2V

Alpha-Top (Sea&Land Alliance)

Performance Specification

Mar. 41.4		V_{max}	ı _x I _{max}	I _{hold}	I _{trip}	I _{trip} P _d		Maximum Time To Trip		Resistance		Agency Approval	
Model	Marking			@25°C	@25°C	Max.	Current	Time	$\mathrm{Ri}_{\mathrm{min}}$	R1max	UL	TUV	
		(Vdc)	(A)	(A)	(A)	(W)	(A)	(Sec)	(Ω)	(Ω)	0_		
SMD1210-110-13.2V	αH	13.2	100	1.10	2.20	0.6	8.0	0.30	0.050	0.210			

Ihold = Hold Current. Maximum current device will not trip in 25°C still air.

Itrip = Trip Current. Minimum current at which the device will always trip in 25°C still air.

Vmax = Maximum operating voltage device can withstand without damage at rated current (Imax).

Imax = Maximum fault current device can withstand without damage at rated voltage (Vmax).

Pd = Power dissipation when device is in the tripped state in 25°C still air environment at rated voltage.

Rimin/max = Minimum/Maximum device resistance prior to tripping at 25°C.

R1_{max} = Maximum device resistance is measured one hour post reflow.

CAUTION: Operation beyond the specified ratings may result in damage and possible arcing and flame.

Environmental Specifications

Test	Conditions	Resistance change				
Passive aging	+85°C, 1000 hrs.	±5% typical				
Humidity aging	+85°C, 85% R.H., 168 hours	±5% typical				
Thermal shock	+85°C to -40°C, 20 times	±33% typical				
Resistance to solvent	MIL-STD-202, Method 215	No change				
Vibration	MIL-STD-202,Method 201	No change				
Ambient operating conditions : - 40 °C to +85 °C						
Maximum surface temperature of the device in the tripped state is 125 °C						

Agency Approvals :

Regulation/Standard:



2015/863/EU

EN14582

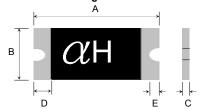
ار Versus Temperature

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Model	Maximum ambient operating temperature (T _{mao}) vs. hold current (I _{hold})									
	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C	
SMD1210-110-13.2V	1.69	1.48	1.29	1.10	0.88	0.76	0.65	0.57	0.43	

Construction And Dimension (Unit:mm)

Model		A	В		С		D	E
Woder	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Min.
SMD1210-110-13.2V	3.00	3.43	2.35	2.80	0.50	1.20	0.30	0.10

Dimensions & Marking



α = TrademarkH = Part identification

Recommended Pad Layout (mm) 1.0±0.1 1.0±0.1 1.0±0.1 1.0±0.1 2.0±0.1

Termination Pad Characteristics

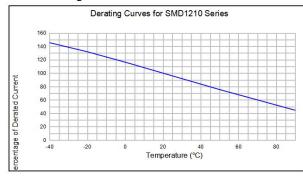
Terminal pad materials : Tin-plated Nickel-Copper

Terminal pad solderability: Meets EIA specification RS186-9E and ANSI/J-STD-002 Category 3.

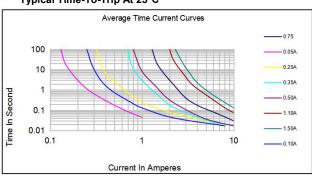
Rework

Use standard industry practices, the removal device must be replaced with a fresh one.

Thermal Derating Curve



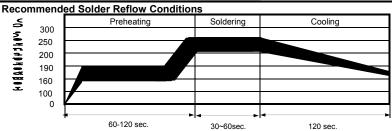
Typical Time-To-Trip At 25°C



NARNING:

- · Use PPTC beyond the maximum ratings or improper use may result in device damage and possible electrical arcing and flame.
- PPTC are intended for protection against occasional over current or over temperature fault conditions and should not be used when repeated fault conditions or prolonged trip events are anticipated.
- Device performance can be impacted negatively if devices are handled in a manner inconsistent with recommended electronic, thermal, and mechanical procedures for electronic components.

 Use PPTC with a large inductance in circuit will generate a circuit voltage (L di/dt) above the rated voltage of the PPTC.
- Avoid impact PPTC device its thermal expansion like placed under pressure or installed in limited space.
- · Contamination of the PPTC material with certain silicon based oils or some aggressive solvents can adversely impact the performance of the devices. PPTC SMD can be cleaned by standard methods.
- · Requests that customers comply with our recommended solder pad layouts and recommended reflow profile. Improper board layouts or reflow profile could negatively impact solderability performance of our devices.



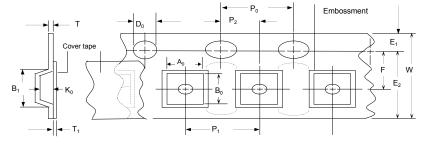
- Recommended reflow methods : IR, vapor phase oven, hot air oven.
- Devices are not designed to be wave soldered to the bottom side of the board.
- Recommended maximum paste thickness is 0.25 mm (0.010 inch).
- Devices can be cleaned using standard method and solvents.

Note: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

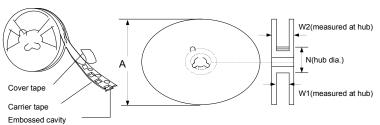
Tape And Reel Specifications (mm)

Governing Specifications	EIA 481-2
W	8.0 ± 0.20
P0	4.0 ± 0.10
P1	4.0 ± 0.10
P2	2.0 ± 0.10
A0	2.82 ± 0.10
B0	3.52± 0.10
B1max.	4.35
D0	1.5 + 0.1, -0.0
F	7.5 ± 0.05
E1	1.75 ± 0.10
E2min.	6.25
Tmax.	0.6
T1max.	0.1
K0	0.90 ± 0.1
Leader min.	390
Trailer min.	160
Reel Dimensions	
A max.	178
N min.	50
W1	8.4 + 1.5, -0.0
W2max.	22.4

EIA Tape Component Dimensions



EIA Reel Dimensions



Storage And Handling

- Storage conditions: 40°C max, 70% R.H.
- Devices may not meet specified performance if storage conditions are exceeded.

Order Information Packaging

SMD1210	110-13.2V	Tape & Reel Quantity
Product name	Hold	
Size 3225 mm / 1210 inch	Current	4,500 pcs/reel
SMD: surface mount device	1.10A	

Tape & reel packaging per EIA481-1

Labeling Information

